

Appl. No. 10/552,540
Amdt. Dated February 19, 2008
Reply to Office Action of November 16, 2007

Attorney Docket No. 81844.0044
Customer No. 26021

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:
Shigeru TANAKA, et al.
Serial No.: 10/552,540
Confirmation No.: 2300
Filed: October 11, 2005
For: THERMOSETTING RESIN
COMPOSITION, MULTILAYER BODY
USING SAME, AND CIRCUIT BOARD

Art Unit: 1796
Examiner: Patrick Dennis
Niland

AMENDMENT UNDER 37 C.F.R. § 1.116

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

DO NOT ENTER: /P.N./ 02/26/2008

Dear Sir:

In response to the Final Office Action dated November 16, 2007, due February 16, 2008 (Saturday), please amend the above-referenced application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 27 of this paper.